- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

#### description

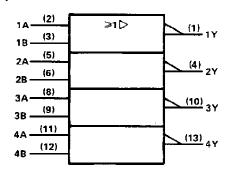
These devices contain four independent 2-input-NOR line drivers. They perform the Boolean function  $Y = \overline{A} + \overline{B}$  or  $Y = \overline{A} \cdot \overline{B}$ . The SN54128 is designed to drive 75 ohm lines. The SN74128 is designed to drive 50 ohm lines.

The SN54128 is characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to 125 $^{\circ}\text{C}$ . The SN74128 is characterized for operation from 0 $^{\circ}\text{C}$  to 70 $^{\circ}\text{C}$ .

#### logic diagram (each driver)



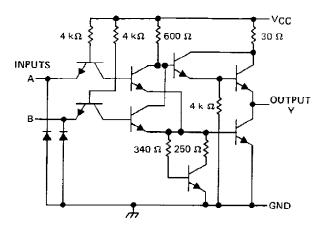
### logic symbol†



<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### SN54128 . . . J OR W PACKAGE **SN74128...N PACKAGE** (TOP VIEW) 17 □1 / 14口 Vcc 13 4Y 1A 🛮 2 18 □3 12 4B 2Y **□**4 11 4A 2A 🗆 5 10 3Y 28 □ 6 9 3B GND ☐ 7 8 3A

### schematic (each driver)



Resistor values shown are nominal,

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Operating free-air temperature range:	SN54'	- 55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range	· · · · · · · · · · · · · · · · · · ·	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## SN54128, SN74128 LINE DRIVERS

#### recommended operating conditions

		L	SN54128			SN74128			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4,5	5	5.5	4.75	5	5.25	V	
$V_{IH}$	High-level input voltage	2		-	2			V	
VIL	Low-level input voltage			0.8			0.8	V	
ЮН	High-level output current			- 29			- 42.4	mA	
loL	Low-level output current			48			48	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	ş t	MIN	TYP‡	MAX	UNIT
ViK	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA				1.5	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub>	= - 2.4 mA	2.4	.4 3,4		
$v_{OH}$	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.4 V, I <sub>OH</sub>	- 13.2 mA	2.4			V
	$V_{CC} = MIN$ , $V_{IL} = 0.4 \text{ V}$ , $I_{OH} = 0.4 \text{ V}$	= MAX	2			1
VOL	VCC = MIN, VIH = 2 V, IOL	≈ 4B mA		0.26	0.4	V
ł į	V <sub>CC</sub> = MAX. V <sub>1</sub> = 5.5 V				1	mΑ
l <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V				40	μА
<u> </u>	V <sub>CC</sub> = MAX, V <sub>1</sub> = 0.4 V				- 1.6	mA
los§	V <sub>CC</sub> = MAX		-70		180	mA
1ссн	VCC = MAX			12	21	mA
ICCL	V <sub>CC</sub> = MAX			33	57	mΑ

t For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	TEST CONDITIONS				UNIT
tPLH		Υ .	R <sub>L</sub> = 133 Ω,			6	9	ns
<sup>₹</sup> PHL	A or B			C <sub>L</sub> ≈ 50 pF		8	12	∩s
₹PLH .	70,5		$R_1 = 133 \Omega$ ,	0 150 - 5		10	15	ns
<sup>t</sup> PHL			HE - 133 38,	C <sub>L</sub> = 150 pF		12	18	П5

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

 $<sup>\</sup>pm$  All typical values are at VCC = 5 V, TA = 25°C.  $\S$  Not more than one output should be shorted at a time.



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## **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9861101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J	Samples
5962-9861101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W	Samples
5962-9861101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W	Samples
SN54128J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54128J	Samples
SN54128J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54128J	Samples
SN74128D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74128	Samples
SN74128D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74128	Samples
SN74128N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74128N	Samples
SN74128N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74128N	Samples
SN74128NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN74128	Samples
SN74128NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN74128	Samples
SNJ54128J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J	Samples
SNJ54128J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QC A SNJ54128J	Samples
SNJ54128W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QD A SNJ54128W	Samples
SNJ54128W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9861101QD A	Samples

## **PACKAGE OPTION ADDENDUM**

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Orderable Device	Status	Package Type	Package Drawing	Pins Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
						(6)				
									SNJ54128W	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54128, SN74128:

Catalog: SN74128

# **PACKAGE OPTION ADDENDUM**

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Military : SN54128

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74128NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 7-Dec-2024



### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74128NSR	SOP	NS	14	2000	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 7-Dec-2024

### **TUBE**



### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9861101QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74128D	D	SOIC	14	50	506.6	8	3940	4.32
SN74128N	N	PDIP	14	25	506	13.97	11230	4.32
SN74128N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54128W	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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